Call for Abstracts (due January 30, 2019)

ASME 2019 INTERPACK®

International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems

October 7-9, 2019 at Hilton Anaheim in Anaheim, California, USA

https://event.asme.org/interpack

InterPACK is the premier international conference for exchange of state-of-the-art knowledge in research, development, manufacturing, applications of electronics and photonics packaging and heterogeneous integration. InterPACK is the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The international nature of the meeting has been highly beneficial in promoting global interactions between Industry, Academia and National Labs. In addition to paper presentations and exhibits, InterPACK 2019 will include panel discussions, workshops, tutorials, keynote and technology talks by prominent speakers, and a Joint Industry-Academia-National Lab poster session. **Abstracts (<400 words) for papers, posters and presentation-only contributions are solicited by January 30, 2019. Submissions are encouraged (but not limited to) the general track areas below.**

Heterogeneous Integration

Advanced Packaging, Thermal Management, Die Stacking, Multichip Modules, Interconnect Technology, Substrate Technology, Through-Silicon Vias, Wafer Level Packaging (Fan-in, Fan-out), Panel Level Packaging, System in Package, Microsystems Integration, RF Packaging, Advanced Materials and Processes, Chip Package Interaction, Modeling, Characterization and Reliability for Integrated Devices, Electronic Materials, Underfills, Molding Compounds, Substrates, Dielectrics

Servers of the Future, Edge and Cloud Computing

Data Centers and Energy-Efficient Electronic Systems, Cloud Computing Hardware, Edge-to-Cloud Systems, Rack-Level Cooling, Thermal Interface Materials and Thermal Underfills, Fans and Pumps, Thermosyphons and Refrigeration, Exaflop Computing Systems, Memory, Connectors, Advanced Substrates, Novel Cooling Techniques and Heat Transport, Heat Exchangers, Device-to-System Level Packaging, Multiscale Thermal Modeling

Internet of Things

IoT Device Design and Fabrication, IoT Sensing, Flexible Substrates, Thermal and Mechanical Properties

Flexible and Wearable Electronics

Fabrication, Printed Electronics, Substrate Materials, Thin-Die Handling, Hermetic Packaging, Interconnects, Sensors and Actuators, RF Resonators, Implantable Medical Devices, Microfluidic Systems, Biosystems and Biomedicine, Prognostics and Health Monitoring, Integration, Materials Interactions and Characterization, Reliability of Devices/ Systems, Reliability Modelling and Simulation, Reliability Test Methods/ Solder Joint Reliability

Photonics and Optics

Photonics Packaging, Integrated Photonics, Optical Integration, Thermal and Mechanical Challenges for Optical Photonics Integration, Light Emitting and Laser Diodes - Thermal, Mechanical, Reliability and Integration Aspects

Power Electronics

Wide-Bandgap Semiconductor Packaging, Harsh Environment Sensors, High-Temperature Electronics, Interconnects, Novel Materials, Novel Devices, Thermal Management, Integrated Heat Sinks, Thermal Design and Modeling, High-Voltage Packaging, Reliability Modeling and Simulation, Package and Component Reliability and Prognostics, Interface/ Interconnect Reliability

Energy Conversion and Storage

Energy Harvesting, Energy Storage, Thermoelectrics, Photovoltaics, Fuel Cells, Batteries, Integration in Systems, Safety, Thermal Management, Fast Charging, Diagnostics, Design, Manufacturing, Recycling

Autonomous, Hybrid, and Electric Vehicles

Electronics for Vehicle Electrification, High-Temperature Sensors, RADAR, LIDAR, Advanced Driver Assistance System (ADAS) Electronics, MEMS Packaging, Control Systems, Electronic Materials, Nanosatellites, Unmanned Aerial Vehicle Electronics, Hybrid Packaging, Prognostic Health Monitoring, Vehicle Charging, Wireless Power Transfer, Electric Motors/ Machines, Motor Control Sensing, Battery Management

Publication Schedule

Abstract Submission:	January 30, 2019
Draft Paper Submission:	April 30, 2019
Draft Paper Acceptance Notification:	June 10, 2019
Submission of Revised Draft Papers:	June 30, 2019
Submission of Final Paper and Copyright:	July 15, 2019
Posters and Presentation-only Abstract:	July 15, 2019

Direct general inquiries to:

General Chair: Sreekant Narumanchi (sreekant.narumanchi@nrel.gov)
General Vice-Chairs: Samuel Graham (sgraham@gatech.edu), Xiaobing Luo (luoxb@hust.edu.cn)
Program Chair: Ankur Jain (jaina@uta.edu)
Program Co-Chairs: Jin Yang (jin1.yang@intel.com), Kazuyoshi Fushinobu (fushinobu.k.aa@m.titech.ac.jp), Tomoyuki Hatakeyama (hatake@pu-toyama.ac.jp)